



#16/B

4/30/02
John H.

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Inventors: Masanori Minamio, et al.

Art Unit: 2815

Appln. No.: 09/380,312

Examiner: L.C. Cruz

Filed: August 31, 1999

For: RESIN MOLDED TYPE SEMICONDUCTOR DEVICE AND
METHOD OF MANUFACTURE OF SAME

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TECHNICAL CENTER 2800

AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the Office Action mailed December 20, 2001, the Applicants hereby petition for a one month extension of time and request amendment of the above-identified application as follows:

IN THE CLAIMS:

Please amend claims 1-3 and 8-10 to read as follows (Exhibit I contains a marked up version):

1. (Amended) A resin molded type semiconductor device comprising: a semiconductor chip which is mounted on a die pad portion of a lead frame; thin metal wires which electrically connect terminals of an upper face of said semiconductor chip to inner lead portions of the lead frame; a sealing resin which seals